

Declaration and Power of Attorney for Patent Application

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

MULTILAYER WIRING BOARD

The specification of which

☐ is attached hereto.

☐ was filed on _____

as Application Serial No. _____

and was amended on _____

(if applicable)

☒ was filed as PCT international application

No. PCT/JP2005/002205 on February 15, 2005

and was amended under PCT Article 19 on _____

(if applicable)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

2004-051554
(Number)

Japan
(Country)

26/February/2004
(Day/Month/Year Filed)

☒ Yes ☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes ☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes ☐ No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status) (patented, pending, abandoned)
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_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status) (patented, pending, abandoned)
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the practitioners associated with

Customer Number 28289

to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith.

Customer Number 28289 identifies the law firm of **WEBB ZIESENHEIM LOGSDON ORKIN AND HANSON, P.C.** whose address is 700 Koppers Building, 436 Seventh Avenue, Pittsburgh, Pennsylvania 15219-1818, Telephone No. 412-471-8815

Please send all correspondence to Customer Number 28289.

Please direct all telephone calls to Kent E. Baldauf, at telephone number (412) 471-8815.

Full name of sole or first inventor Katsuhiko HAYASHI	
Inventor's signature <i>Katsuhiko Hayashi</i>	Date August 14, 2006
Residence Ageo-shi, Saitama, Japan	
Citizenship Japan	
Post Office Address c/o MITSUI MINING & SMELTING CO., LTD., Corporate R&D Center, 1333-2, Haraichi, Ageo-shi, Saitama 3620021 Japan	
Full name of second joint inventor, if any	
Inventor's signature	Date
Residence	
Citizenship	
Post Office Address	